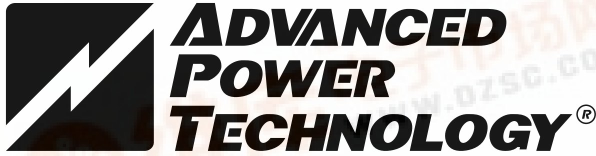
查询APT5010B2LC供应商　　捷多邦，专业PCB打样工厂，24小时加急出货

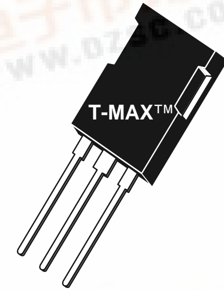


APT5010B2LC

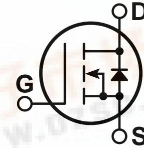
500V　47A　0.100 Ω

POWER MOS VI™

Power MOS VI™ is a new generation of low gate charge, high voltage N-Channel enhancement mode power MOSFETs. Lower gate charge is achieved by optimizing the manufacturing process to minimize C_{iss} and C_{rss}. Lower gate charge coupled with Power MOS VI™ optimized gate layout, delivers exceptionally fast switching speeds.



- **Lower Gate Charge**
- **Faster Switching**
- **100% Avalanche Tested**
- **Lower Input Capacitance**
- **Easier To Drive**
- **Popular TMax Package**



PRELIMINARY

MAXIMUM RATINGS

All Ratings: T_C = 25°C unless otherwise specified.

Symbol	Parameter	APT5010B2LC	UNIT
V_{DSS}	Drain-Source Voltage	500	Volts
I_D	Continuous Drain Current @ T_C = 25°C	47	Amps
I_{DM}	Pulsed Drain Current ①	188	
V_{GS}	Gate-Source Voltage Continuous	±30	Volts
V_{GSM}	Gate-Source Voltage Transient	±40	
P_D	Total Power Dissipation @ T_C = 25°C	520	Watts
	Linear Derating Factor	4.16	W/°C
T_J,T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	°C
T_L	Lead Temperature: 0.063" from Case for 10 Sec.	300	
I_{AR}	Avalanche Current ① (Repetitive and Non-Repetitive)	47	Amps
E_{AR}	Repetitive Avalanche Energy ①	50	mJ
E_{AS}	Single Pulse Avalanche Energy ④	2500	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage (V_{GS} = 0V, I_D = 250μA)	500			Volts
$I_{D(on)}$	On State Drain Current ② (V_{DS} > $I_{D(on)}$ x $R_{DS(on)}$ Max, V_{GS} = 10V)	47			Amps
$R_{DS(on)}$	Drain-Source On-State Resistance ② (V_{GS} = 10V, 0.5 $I_{D[Cont.]}$)			0.100	Ohms
I_{DSS}	Zero Gate Voltage Drain Current (V_{DS} = V_{DSS}, V_{GS} = 0V)			25	μA
	Zero Gate Voltage Drain Current (V_{DS} = 0.8 V_{DSS}, V_{GS} = 0V, T_C = 125°C)			250	
I_{GSS}	Gate-Source Leakage Current (V_{GS} = ±30V, V_{DS} = 0V)			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage (V_{DS} = V_{GS}, I_D = 2.5mA)	3		5	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - http://www.advancedpower.com

USA
405 S.W. Columbia Street　Bend, Oregon 97702-1035　Phone: (541) 382-8028　FAX: (541) 388-0364
EUROPE

DYNAMIC CHARACTERISTICS

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C_{iss}	Input Capacitance	V_{GS} = 0V V_{DS} = 25V f = 1 MHz		5120		pF
C_{oss}	Output Capacitance			1030		
C_{rss}	Reverse Transfer Capacitance			190		
Q_g	Total Gate Charge ③	V_{GS} = 10V V_{DD} = 0.5 V_{DSS} $I_D = I_{D[Cont.]}$ @ 25°C		145		nC
Q_{gs}	Gate-Source Charge			26		
Q_{gd}	Gate-Drain ("Miller") Charge			73		
$t_{d(on)}$	Turn-on Delay Time	V_{GS} = 15V V_{DD} = 0.5 V_{DSS} $I_D = I_{D[Cont.]}$ @ 25°C R_G = 0.6Ω		11		ns
t_r	Rise Time			12		
$t_{d(off)}$	Turn-off Delay Time			30		
t_f	Fall Time			6		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
I_S	Continuous Source Current (Body Diode)			47	Amps
I_{SM}	Pulsed Source Current ① (Body Diode)			188	
V_{SD}	Diode Forward Voltage ② (V_{GS} = 0V, $I_S = -I_{D[Cont.]}$)			1.3	Volts
t_{rr}	Reverse Recovery Time ($I_S = -I_{D[Cont.]}$, dI_S/dt = 100A/µs)		570		ns
Q_{rr}	Reverse Recovery Charge ($I_S = -I_{D[Cont.]}$, dI_S/dt = 100A/µs)		11.0		µC

PRELIMINARY

THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.24	°C/W
$R_{\theta JA}$	Junction to Ambient			40	

① Repetitive Rating: Pulse width limited by maximum junction temperature.

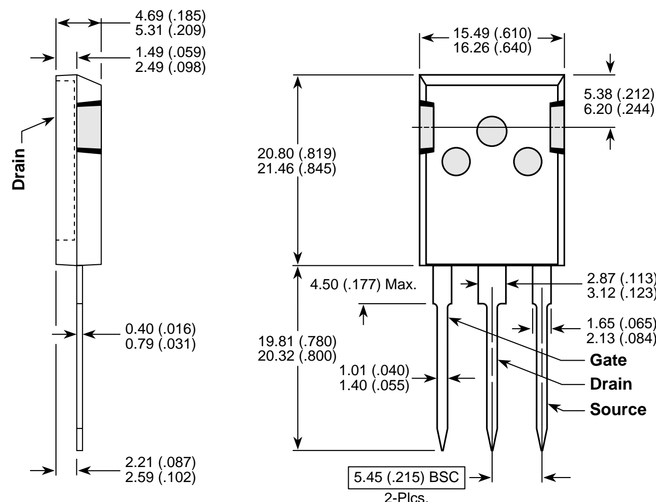
② Pulse Test: Pulse width < 380 µS, Duty Cycle < 2%

③ See MIL-STD-750 Method 3471

④ Starting T_j = +25°C, L = 2.26mH, R_G = 25Ω, Peak I_L = 47A

APT Reserves the right to change, without notice, the specifications and information contained herein.

T-MAX™ Package Outline



Dimensions in Millimeters and (Inches)